

This chapter describes power management in Stratix® IV devices. Stratix IV devices offer programmable power technology options for low-power operation. You can use these options, along with speed grade choices, in different permutations to give the best power and performance combination. For thermal management, use the Stratix IV internal temperature sensing device (TSD) with built-in analog-to-digital converter (ADC) circuitry or external TSD with an external temperature sensor to easily incorporate this feature in your designs. Being able to monitor the junction temperature of the device at any time also offers the ability to control air flow to the device and save power for the whole system.

Overview

Stratix IV FPGAs deliver a breakthrough level of system bandwidth and power efficiency for high-end applications, allowing you to innovate without compromise. Stratix IV devices use advanced power management techniques to enable both density and performance increases while simultaneously reducing power dissipation.

The total power of an FPGA includes static and dynamic power.

- Static power is the power consumed by the FPGA when it is configured but no clocks are operating.
- Dynamic power is the switching power when the device is configured and running. You configure dynamic power with the equation shown in [Equation 13–1](#).

Equation 13–1. Dynamic Power Equation *(Note 1)*

$$P = \frac{1}{2}CV^2 \times \text{frequency}$$

Note to Equation 13–1:

(1) P = power; C = load capacitance; and V = supply voltage level.

[Equation 13–1](#) shows that frequency is design dependant. However, you can vary the voltage to lower dynamic power consumption by the square value of the voltage difference. Stratix IV devices minimize static and dynamic power with advanced process optimizations and programmable power technology. These technologies enable Stratix IV designs to optimally meet design-specific performance requirements with the lowest possible power.

The Quartus® II software optimizes all designs with Stratix IV power technology to ensure performance is met at the lowest power consumption. This automatic process allows you to concentrate on the functionality of the design instead of the power consumption of the design.

Power consumption also affects thermal management. Stratix IV devices offer a TSD feature that self-monitors the device junction temperature and can be used with external circuitry for other activities, such as controlling air flow to the Stratix IV FPGA.

This chapter contains the following sections:

- “Stratix IV Power Technology”
- “Stratix IV External Power Supply Requirements”
- “Temperature Sensing Diode”

Stratix IV Power Technology

The following sections describe Stratix IV programmable power technology.

Programmable Power Technology

Stratix IV devices offer the ability to configure portions of the core, called tiles, for high-speed or low-power mode of operation performed by the Quartus II software without user intervention. Setting a tile to high-speed or low-power mode is accomplished with on-chip circuitry and does not require extra power supplies brought into the Stratix IV device. In a design compilation, the Quartus II software determines whether a tile must be in high-speed or low-power mode based on the timing constraints of the design.

 For more information about how the Quartus II software uses programmable power technology when compiling a design, refer to *AN 514: Power Optimization in Stratix IV FPGAs*.

A Stratix IV tile can consist of the following:

- Memory logic array block (MLAB)/logic array block (LAB) pairs with routing to the pair
- MLAB/LAB pairs with routing to the pair and to adjacent digital signal processing (DSP)/memory block routing
- TriMatrix memory blocks
- DSP blocks

All blocks and routing associated with the tile share the same setting of either high-speed or low-power mode. By default, tiles that include DSP blocks or memory blocks are set to high-speed mode for optimum performance. Unused DSP blocks and memory blocks are set to low-power mode to minimize static power. Clock networks do not support programmable power technology.

With programmable power technology, faster speed grade FPGAs may require less power because there are fewer high-speed MLAB and LAB pairs, when compared with slower speed grade FPGAs. The slower speed grade device may have to use more high-speed MLAB and LAB pairs to meet performance requirements, while the faster speed grade device can meet performance requirements with MLAB and LAB pairs in low-power mode.

The Quartus II software sets unused device resources in the design to low-power mode to reduce static and dynamic power. It also sets the following resources to low-power mode when they are not used in the design:

- LABs and MLABs
- TriMatrix memory blocks
- DSP blocks

If a phase-locked loop (PLL) is instantiated in the design, asserting the `areset` pin high keeps the PLL in low-power mode.

Table 13-1 lists the available Stratix IV programmable power capabilities. Speed grade considerations can add to the permutations to give you flexibility in designing your system.

Table 13-1. Programmable Power Capabilities in Stratix IV Devices

Feature	Programmable Power Technology
LAB	Yes
Routing	Yes
Memory Blocks	Fixed setting (1)
DSP Blocks	Fixed setting (1)
Global Clock Networks	No

Note to Table 13-1:

- (1) Tiles with DSP blocks and memory blocks that are used in the design are always set to high-speed mode. By default, unused DSP blocks and memory blocks are set to low-power mode.

Stratix IV External Power Supply Requirements

This section describes the different external power supplies required to power Stratix IV devices. You can supply some of the power supply pins with the same external power supply, provided they have the same voltage level.

- For power supply pin connection guidelines and power regulator sharing, refer to the *Stratix IV GX and Stratix IV E Device Family Pin Connection Guidelines*.
- For each Altera recommended power supply's operating conditions, refer to the *DC and Switching Characteristics for Stratix IV Devices* chapter.

Temperature Sensing Diode

The Stratix IV TSD uses the characteristics of a PN junction diode to determine die temperature. Knowing the junction temperature is crucial for thermal management. Historically, junction temperature is calculated using ambient or case temperature, junction-to-ambient (j_a) or junction to-case (j_c) thermal resistance, and device power consumption. Stratix IV devices can either monitor its die temperature with the internal TSD with built-in ADC circuitry or the external TSD with an external temperature sensor. This allows you to control the air flow to the device.

You can use the Stratix IV internal TSD in two different modes of operation—power-up mode and user mode. For power-up mode, the internal TSD reads the die's temperature during configuration if the ALTTEMP_SENSE megafunction is enabled in your design. The ALTTEMP_SENSE megafunction allows temperature sensing during device user mode by asserting the `clken` signal to the internal TSD circuitry. To reduce device static power, disable the internal TSD with built-in ADC circuitry when not in use.

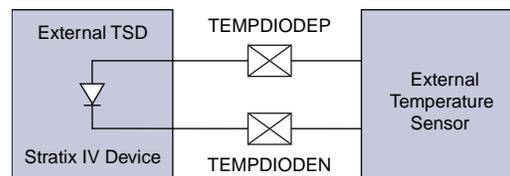
 For more information about using the ALTTEMP_SENSE megafunction, refer to the *Thermal Sensor (ALTTEMP_SENSE) Megafunction User Guide*.

The external temperature sensor steers bias current through the Stratix IV external TSD, which measures forward voltage and converts this reading to temperature in the form of an 8-bit signed number (7 bits plus sign). The 8-bit output represents the junction temperature of the Stratix IV device and can be used for intelligent power management.

External Pin Connections

The Stratix IV external TSD requires two pins for voltage reference. [Figure 13-1](#) shows how to connect the external TSD with an external temperature sensor device. As an example, external temperature sensing devices, such as MAX1619, MAX1617A, MAX6627, and ADT 7411, can be connected to the two external TSD pins for temperature reading.

Figure 13-1. TSD External Pin Connections in Stratix IV Devices



 For more information about the external TSD specification, refer to the *DC and Switching Characteristics for Stratix IV Devices* chapter.

The TSD is a very sensitive circuit that can be influenced by noise coupled from other traces on the board and possibly within the device package itself, depending on your device usage. The interfacing device registers' temperature is based on millivolts (mV) of difference, as seen at the external TSD pins. Switching the I/O near the TSD pins can affect the temperature reading. Altera recommends taking temperature readings during periods of inactivity in the device or use the internal TSD with built-in ADC circuitry.

The following are board connection guidelines for the TSD external pin connections:

- The maximum trace lengths for the TEMPDIODE_P/TEMPDIODE_N traces must be less than eight inches.
- Route both traces in parallel and place them close to each other with grounded guard tracks on each side.
- Altera recommends 10-mils width and space for both traces.
- Route traces through a minimum number of vias and crossunders to minimize the thermocouple effects.
- Ensure that the number of vias are the same on both traces.
- Ensure both traces are approximately the same length.
- Avoid coupling with toggling signals (for example, clocks and I/O) by having the GND plane between the diode traces and the high frequency signals.
- For high-frequency noise filtering, place an external capacitor (close to the external chip) between the TEMPDIODE_P/TEMPDIODE_N trace.
- For Maxim devices, use an external capacitor between 2200 pF to 3300 pF.
- Place a 0.1 uF bypass capacitor close to the external device.
- You can use internal TSD with built-in ADC circuitry and external TSD at the same time.
- If you only use internal ADC circuitry, the external TSD pins (TEMPDIODE_P/TEMPDIODE_N) can connect these pins to GND because the external TSD pins are not used.

 For more information about the TEMPDIODE_P/TEMPDIODE_N pin connection when you are not using an external TSD, refer to the [Stratix IV GX and Stratix IV E Pin Connection Guidelines](#).

 For device specification and connection guidelines, refer to the external temperature sensor device data sheet from the device manufacturer.

Document Revision History

Table 13-2 lists the revision history for this chapter.

Table 13-2. Document Revision History

Date	Version	Changes
February 2011	3.2	<ul style="list-style-type: none"> ■ Applied new template. ■ Minor text edits.
March 2010	3.1	<ul style="list-style-type: none"> ■ Updated the “External Pin Connections” section. ■ Minor text edits.
November 2009	3.0	<ul style="list-style-type: none"> ■ Updated the “Temperature Sensing Diode” and “External Pin Connections” sections. ■ Updated Equation 13-1. ■ Removed Table 13-2: Stratix IV External Power Supply Pins. ■ Minor text edits.
June 2009	2.2	<ul style="list-style-type: none"> ■ Updated the “External Pin Connections” section. ■ Added an introductory paragraph to increase search ability. ■ Removed the Conclusion section.
March 2009	2.1	<ul style="list-style-type: none"> ■ Updated “Temperature Sensing Diode” and “External Pin Connections” sections. ■ Updated Figure 13-1. ■ Removed “Referenced Documents” section.
November 2008	2.0	Minor text edits.
May 2008	1.0	Initial release.